

# HiPerFET™ Power MOSFETs

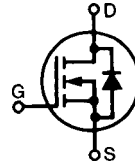
**IXFH/IXFT/IXFX14N100**  
**IXFH/IXFT/IXFX15N100**

$V_{DSS}$	$I_{D25}$	$R_{DS(on)}$
<b>1000 V</b>	<b>14 A</b>	<b>0.75 <math>\Omega</math></b>
<b>1000 V</b>	<b>15 A</b>	<b>0.70 <math>\Omega</math></b>

**$t_{rr} \leq 200$  ns**

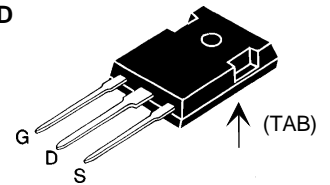
N-Channel Enhancement Mode  
High dv/dt, Low  $t_{rr}$ , HDMOS™ Family

Preliminary data sheet

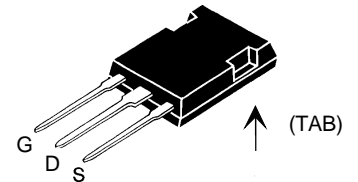


Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	1000	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 1$ M $\Omega$	1000	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_C = 25^\circ\text{C}$	14N100	14 A
		15N100	15 A
$I_{DM}$	$T_C = 25^\circ\text{C}$ , pulse width limited by $T_{JM}$	14N100	56 A
		15N100	60 A
$I_{AR}$	$T_C = 25^\circ\text{C}$	14N100	14 A
		15N100	15 A
$E_{AR}$	$T_C = 25^\circ\text{C}$	45	mJ
dv/dt	$I_S \leq I_{DM}$ , $di/dt \leq 100$ A/ $\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ\text{C}$ , $R_G = 2$ $\Omega$	5	V/ns
$P_D$	$T_C = 25^\circ\text{C}$	360	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	1.6 mm (0.062 in.) from case for 10 s	300	$^\circ\text{C}$
$M_d$	Mounting torque	1.13/10	Nm/lb.in.
Weight		6	g

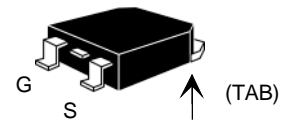
**TO-247 AD  
(IXFH)**



**PLUS 247™  
(IXFX)**



**TO-268 (D3)  
(IXFT)**



### Features

- International standard packages
- Low  $R_{DS(on)}$  HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect
- Fast intrinsic Rectifier

### Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control
- Temperature and lighting controls

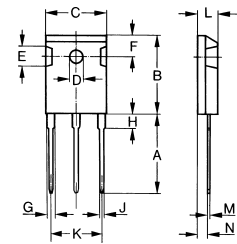
### Advantages

- Easy to mount with 1 screw (TO-247) (isolated mounting screw hole) or mounting clip or spring (PLUS 247™)
- High power surface mountable package
- High power density

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{DSS}$	$V_{GS} = 0$ V, $I_D = 1$ mA	1000		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 4$ mA	2.5		V
$I_{GSS}$	$V_{GS} = \pm 20$ V <sub>DC</sub> , $V_{DS} = 0$			$\pm 100$ nA
$I_{DSS}$	$V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0$ V	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$		250 $\mu\text{A}$
				1 mA
$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300$ $\mu\text{s}$ , duty cycle $d \leq 2$ %	14N100		0.75 $\Omega$
		15N100		0.70 $\Omega$

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$g_{fs}$	$V_{DS} = 10\text{ V}; I_D = 0.5 \cdot I_{D25}$ , pulse test	6	10	S
$C_{iss}$ $C_{oss}$ $C_{rss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		4500	pF
			430	pF
			150	pF
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 2\ \Omega$ (External),		27	ns
			30	ns
			120	ns
			30	ns
$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$		220	nC
			30	nC
			85	nC
$R_{thJC}$ $R_{thCK}$	(TO-247 Case Style)	0.25	0.35	K/W K/W

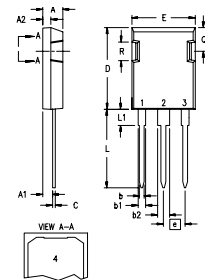
### TO-247 AD (IXFH) Outline



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$I_S$	$V_{GS} = 0\text{ V}$	14N100 15N100		14 A 15 A
$I_{SM}$	Repetitive; pulse width limited by $T_{JM}$	14N100 15N100		56 A 60 A
$V_{SD}$	$I_F = I_S, V_{GS} = 0\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$			1.5 V
$t_{rr}$ $Q_{RM}$ $I_{RM}$	$I_F = I_S$ $-di/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 100\text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$ $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$ $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$		200 ns 350 ns
			1	$\mu\text{C}$
			2	$\mu\text{C}$
			10	A
			15	A

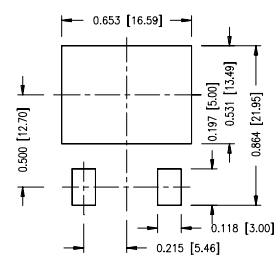
### PLUS247™ (IXFX) Outline



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.83	5.21	.190	.205
A <sub>1</sub>	2.29	2.54	.090	.100
A <sub>2</sub>	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b <sub>1</sub>	1.91	2.13	.075	.084
b <sub>2</sub>	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L <sub>1</sub>	3.81	4.32	.150	.170
Q	5.59	6.20	.220	.244
R	4.32	4.83	.170	.190

TO-268AA (D <sup>3</sup> PAK)		Dim.		Millimeter		Inches	
		Min.	Max.	Min.	Max.	Min.	Max.
	A	4.9	5.1	.193	.201		
	A <sub>1</sub>	2.7	2.9	.106	.114		
	A <sub>2</sub>	.02	.25	.001	.010		
	b	1.15	1.45	.045	.057		
	b <sub>2</sub>	1.9	2.1	.75	.83		
	C	.4	.65	.016	.026		
	D	13.80	14.00	.543	.551		
	E	15.85	16.05	.624	.632		
	E <sub>1</sub>	13.3	13.6	.524	.535		
	e	5.45 BSC		.215 BSC			
	H	18.70	19.10	.736	.752		
	L	2.40	2.70	.094	.106		
	L <sub>1</sub>	1.20	1.40	.047	.055		
	L <sub>2</sub>	1.00	1.15	.039	.045		
	L <sub>3</sub>	0.25 BSC		.010 BSC			
	L <sub>4</sub>	3.80	4.10	.150	.161		

### Min. Recommended Footprint



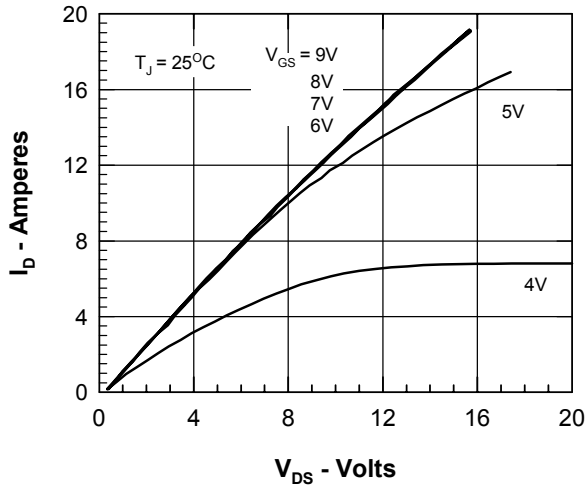


Fig.1 Output Characteristics

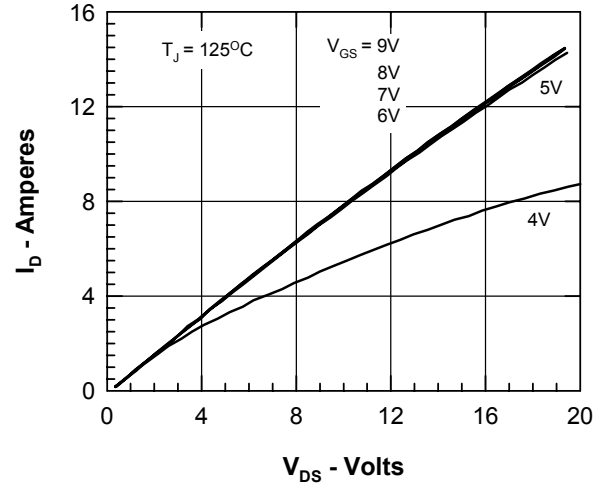


Fig.2 Output characteristics at elevated temperature

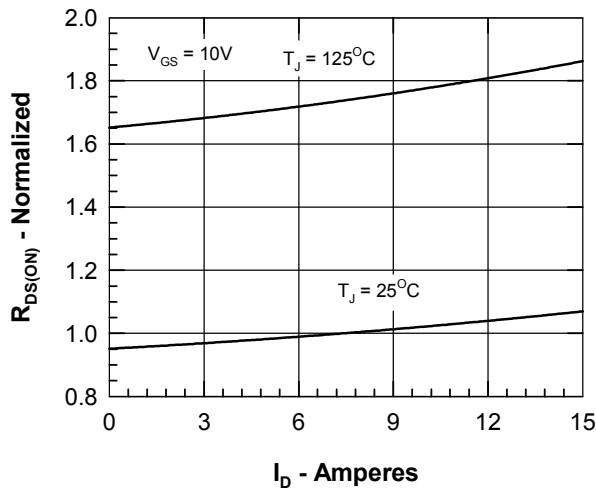


Fig.3  $R_{DS(on)}$  vs. Drain Current

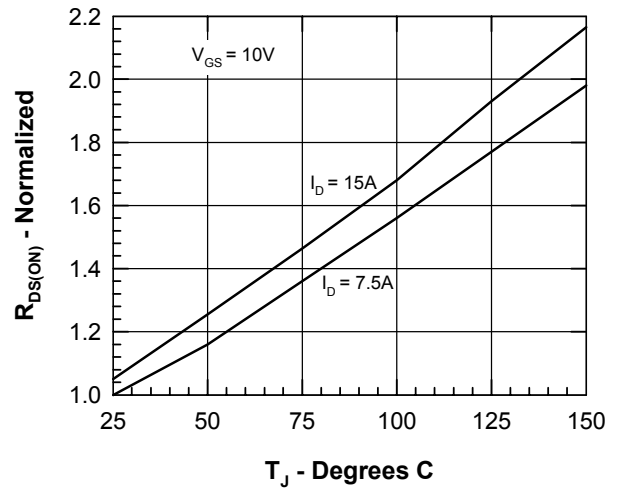


Fig.4 Temperature Dependence of Drain to Source Resistance

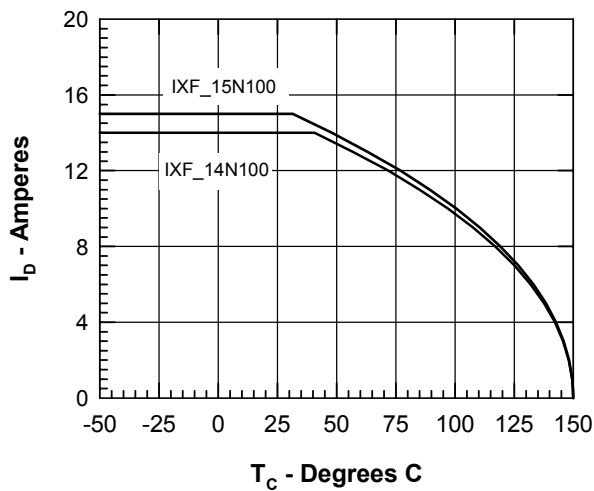


Fig.5 Drain Current vs. Case Temperature

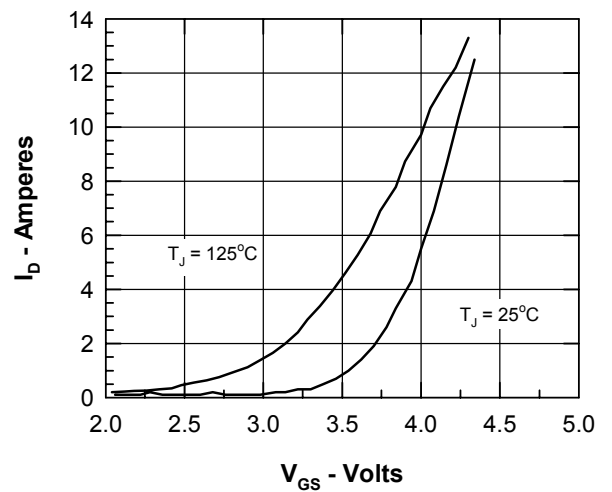


Fig.6 Input admittance

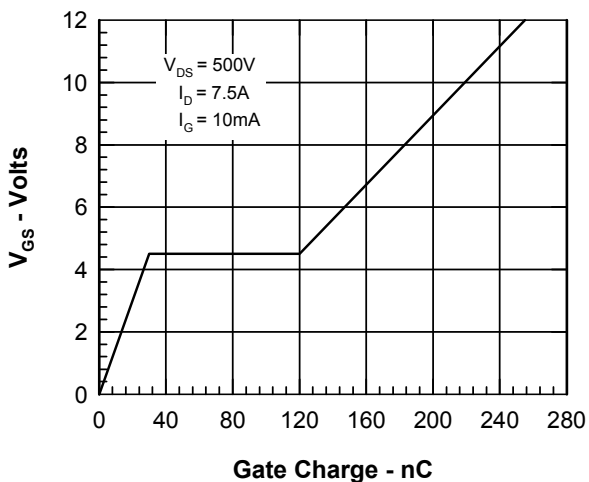


Fig.7 Gate Charge Characteristic Curve

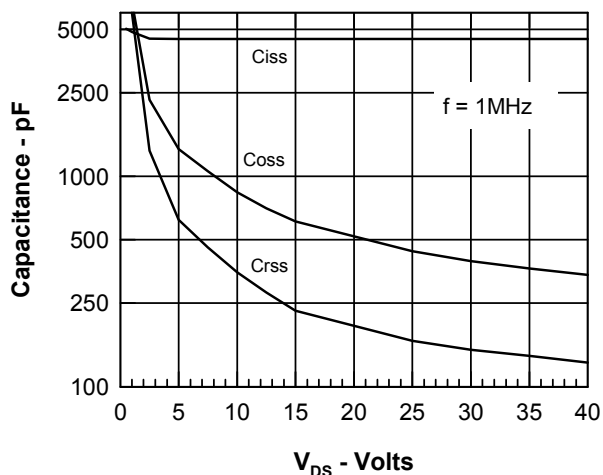


Fig.8 Capacitance Curves

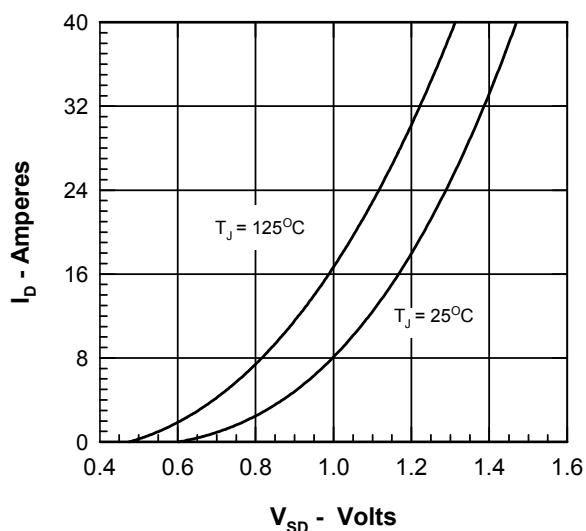


Fig.9 Source current vs Source drain voltage.

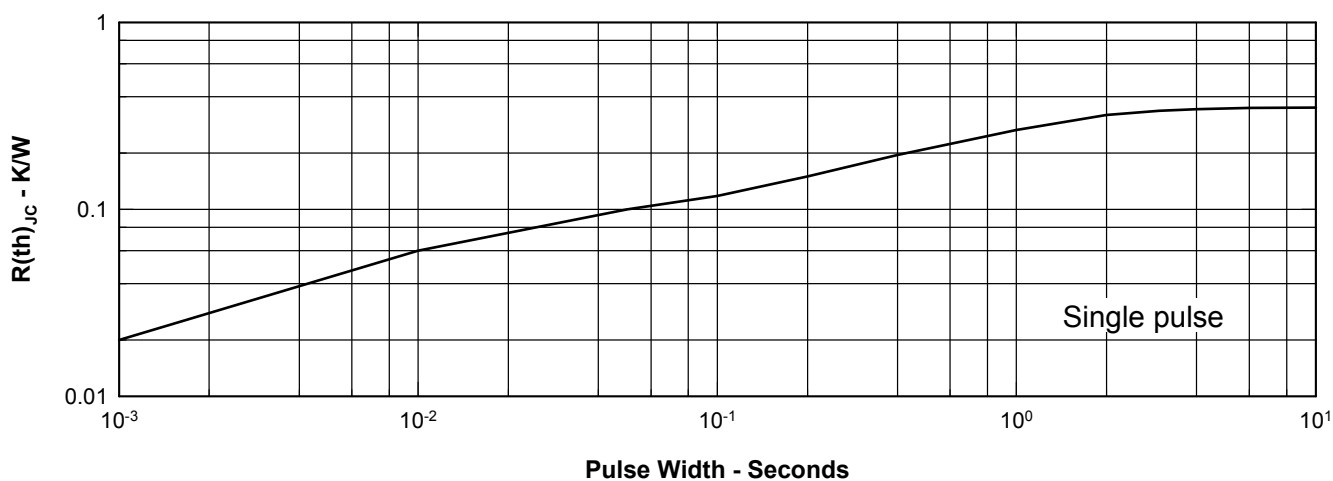


Fig.10 Transient Thermal Impedance